



Typical Applications

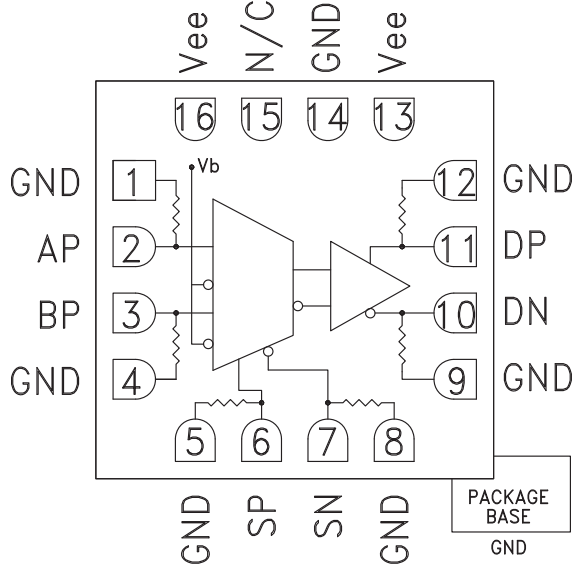
The HMC728LC3C is ideal for:

- 2:1 Multiplexer up to 13 Gbps
- RF ATE Applications
- Broadband Test & Measurement
- Serial Data Transmission up to 13 Gbps
- Redundant Path Switching
- Built-in Test

Features

- Supports High Data Rates: up to 13 Gbps
- Single-ended inputs
- Differential or Single-ended outputs
- Fast Rise and Fall Times: 17 / 15 ps
- Low Power Consumption: 250 mW typ.
- Propagation Delay: 125 ps
- Single Supply: -3.3V
- 16 Lead Ceramic 3x3mm SMT Package: 9mm²

Functional Diagram



General Description

The HMC728LC3C is a 2:1 Selector designed to support data transmission rates of up to 13 Gbps, and selector port operation of up to 13 GHz. The selector routes one of the two single-ended inputs to the differential output upon assertion of the proper select port. All single-ended input signals to the HMC728LC3C are terminated with 50 Ohms to ground on-chip, and may be either AC or DC coupled. The outputs of the HMC728LC3C may be operated either differentially or single-ended. Outputs can be connected directly to a 50 Ohm terminated system, while DC blocking capacitors may be used if the terminating system is 50 Ohms to a non-ground DC voltage. The HMC728LC3C operates from a single -3.3V DC supply and is available in a ceramic RoHS compliant 3x3 mm SMT package.

Electrical Specifications, $T_A = +25^\circ\text{C}$, $V_{ee} = -3.3\text{V}$

Parameter	Conditions	Min.	Typ.	Max	Units
Power Supply Voltage		-3.6	-3.3	-3.0	V
Power Supply Current			76		mA
Maximum Data Rate			13		Gbps
Maximum Select Rate			13		GHz
Maximum Serial Transmission Rate			26		Gbps
Input High Voltage		-0.2		0.5	V
Input Low Voltage		-1.5		-0.4	V
Input Return Loss	Frequency <13 GHz		10		dB
Output Amplitude	Single-Ended, peak-to-peak		550		mVpp
	Differential, peak-to-peak		1100		mVpp
Output High Voltage			-10		mV
Output Low Voltage			-570		mV

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:

SUNSTAR 微波光电 <http://www.hittite.com> / TEL:0755-83396822 FAX:0755-83376182 E-MAIL: szss20@163.com
Order On-line at www.hittite.com

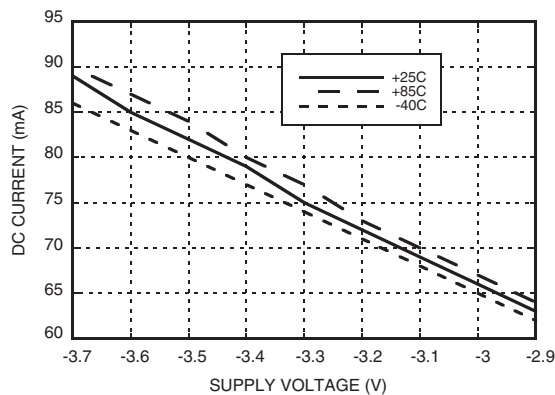


Electrical Specifications (continued)

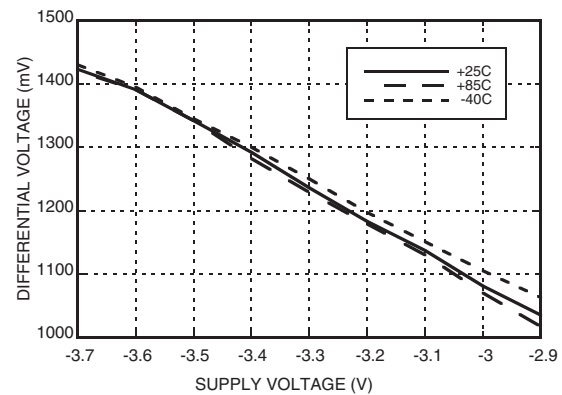
Parameter	Conditions	Min.	Typ.	Max.	Units
Output Rise / Fall Time	Differential, 20% - 80%		17 / 15		ps
Output Return Loss	Frequency <13 GHz		10		dB
Random Jitter, Jr	rms			0.2	ps rms
Deterministic Jitter, Jd	peak-to-peak, 2 ¹⁵ -1 PRBS input [1]		2		ps, pp
Propagation Delay, A or B to D _{OUT} , td			125		ps
Propagation Delay Select to Data, tds			135		ps
Set Up & Hold Time, t _{SH}			6		ps

[1] Deterministic jitter calculated by simultaneously measuring the jitter of a 300 mV, 13 GHz, 2¹⁵-1 PRBS input, and a single-ended output

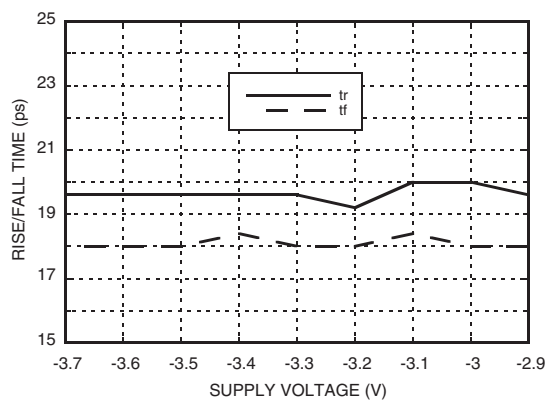
DC Current vs. Supply Voltage [1]



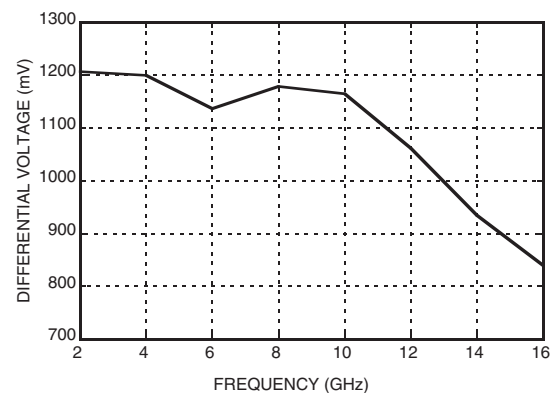
Output Differential vs. Supply Voltage [2]



Rise / Fall Time vs. Supply Voltage [1]



Output Differential vs. Frequency

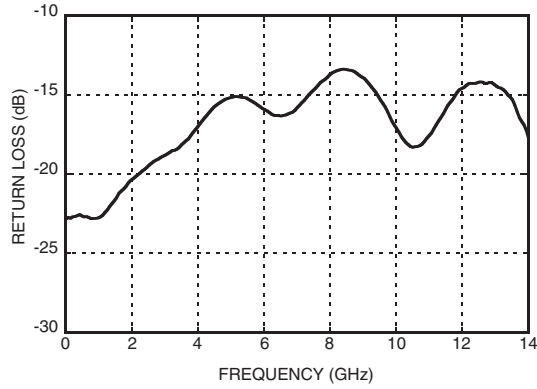


[1] Frequency = 13 GHz

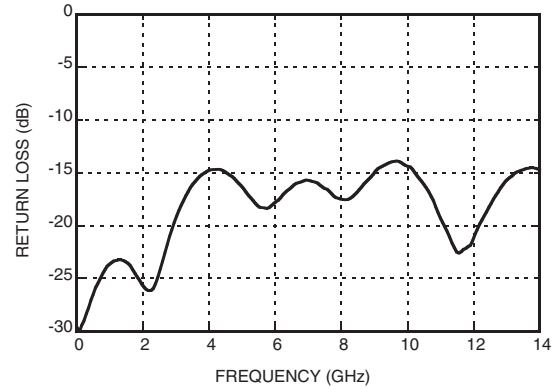
[2] Frequency = 10 GHz



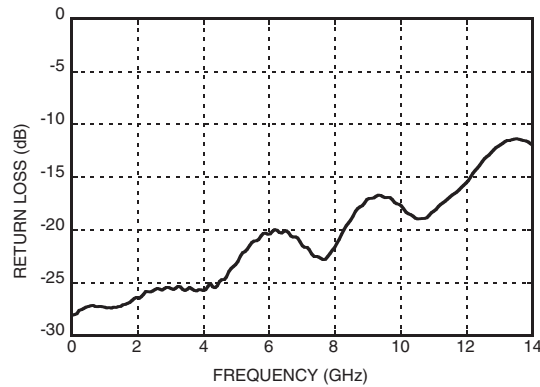
Output Return Loss vs. Frequency



Return Loss of Select Input



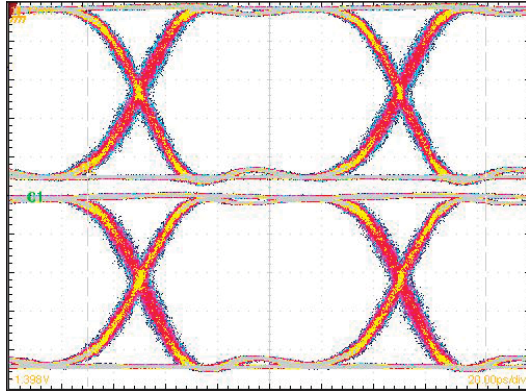
Return Loss of Data Input



[1] Frequency = 13 GHz

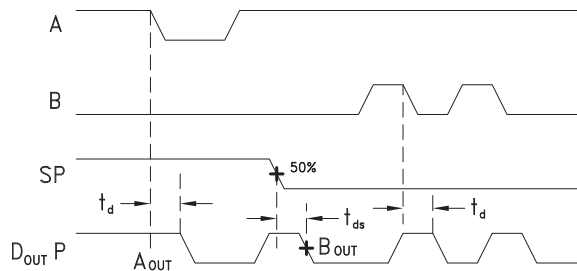


Eye Diagram



[1] Test Conditions:
 Waveform generated with an Agilent N4903A J-Bert.
 Rate = 10 GHz
 Eye Diagram data presented on a Tektronix CSA 8000

Timing Diagram



t_d = propagation delay, A or B to Dout
 t_{ds} = propagation delay, Select to Dout

Truth Table

Inputs		Outputs
SP	SN	DP
L	H	A -> D
H	L	B -> D

H - Positive voltage level
 L - Negative voltage level

Notes:
 D = DP - DN
 S = SP - SN



Absolute Maximum Ratings

Power Supply Voltage (Vee)	-3.75V to +0.5V
Input Signals	-2V to +0.5V
Output Signals	-1.5V to +1V
Storage Temperature	-65°C to +150°C
Operating Temperature	-40°C to +85°C

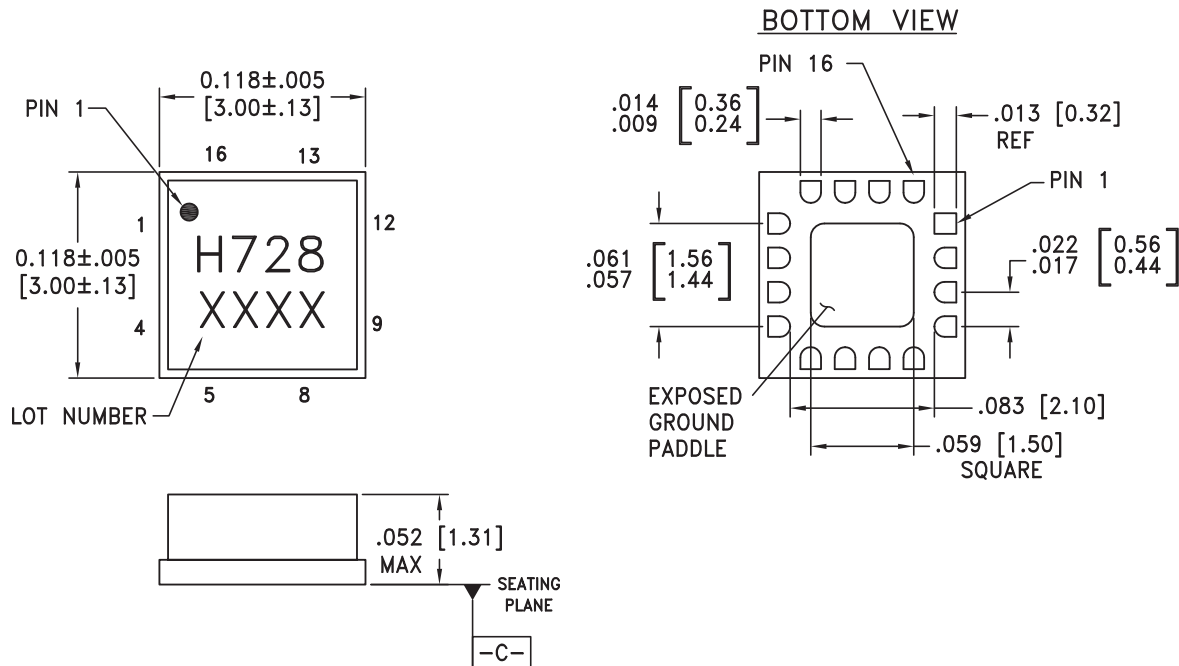


ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

7

HIGH SPEED LOGIC - SMT

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA
2. LEAD AND GROUND PADDLE PLATING:
30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
7. GROUND PADDLE MUST BE SOLDERED TO GND.

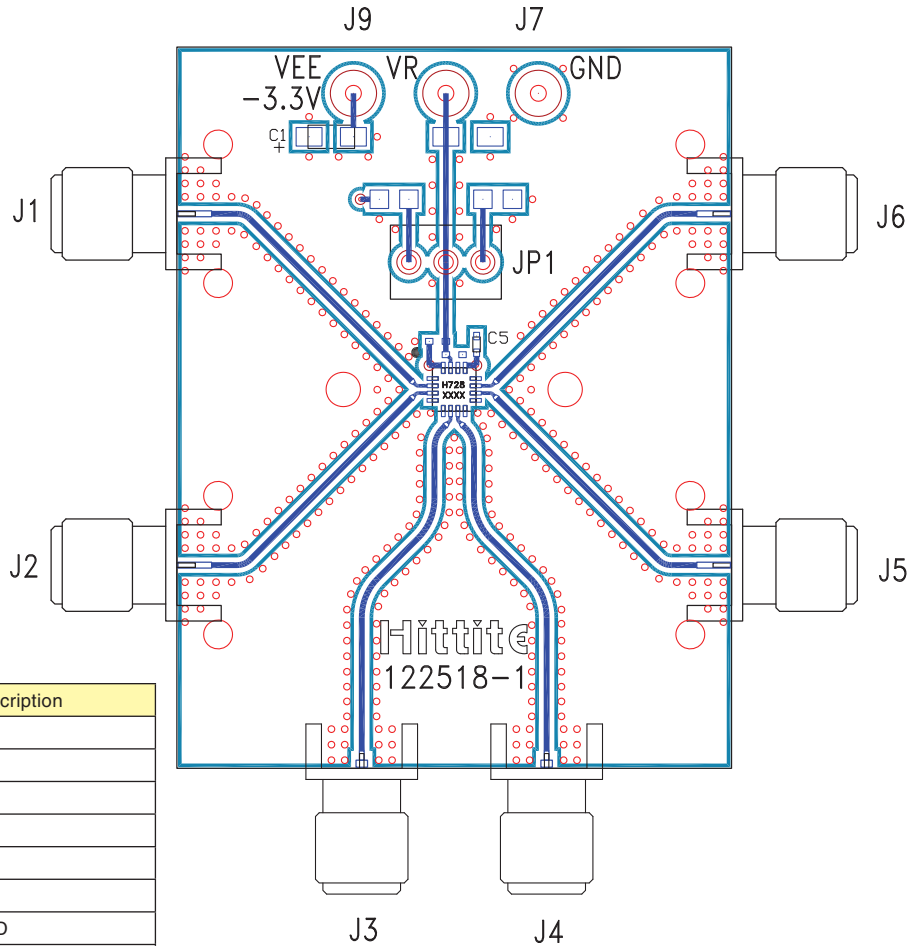


Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 4, 5, 8, 9, 12	GND	Signal Grounds	
2, 3	AP, BP	Data Inputs	
6, 7	SP, SN	Select Inputs	
10, 11	DN, DP	Data Outputs	
13, 16	Vee	Negative Supply	
14, Package Base	GND	Supply Ground	
15	N/C	No Connection	



Evaluation PCB



Item	Description
J1	AP
J2	BP
J3	SP
J4	SN
J5	DN
J6	DP
J7	GND
J9	Vee

List of Materials for Evaluation PCB 122520 [1]

Item	Description
J1 - J6	PCB Mount SMA RF Connectors
J7, J9	DC Pin
C1	4.7 μ F Capacitor, Tantalum
C5	100 pF Capacitor, 0402 Pkg.
U1	HMC728LC3C High Speed Logic, 2:1 Selector
PCB [2]	122518 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed package base should be connected to GND. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



Application Circuit

